

Nagase Acquires 60% Share of Pac Tech GmbH

Nauen, Germany—February 23, 2006—Pac Tech GmbH, Nauen, Germany, announced that Nagase and Co., a major trading company in Japan, has acquired a 60% share of Pac Tech GmbH, for an undisclosed amount. The acquisition was completed on February 10, 2006

Pac Tech GmbH focuses on bumping and packaging based on advanced electroless metallization. It also provides advanced laser bonding and bumping equipment worldwide. Pac Tech GmbH doubled its sales worldwide in 2005 to roughly 14 million Euros.

Nagase began selling Pac Tech GmbH equipment and technology licenses in Japan in 2000. According to Nagase Director Executive Officer Mr. Kazuo Nagashima, “through to addition of Pac Tech’s technology and its market penetration in Japan and China they intend to double their overall sales of back-end equipment and materials over the next three years from approximately 6 billion JPY in 2005.” “Pac Tech’s relationship with Nagase will become even stronger now that they are a major stockholder in the company. Their market presence in the Pacific Rim is strong and will help both company’s gain significant market penetration”, comments Dr. Elke Zake, President of Pac Tech GmbH.

Pac Tech GmbH equipment offers semiconductor manufacturers several distinct advantages over other conventional methods. There is virtually no damage to substrates using their patented contactless method of applying solder-balls to fine and thin materials such as those used in hard disk drive head applications. The electroless wafer bumping method has a strong advantage in achieving short lead-time and low-cost compared to existing electroplating methods. As semiconductor geometries become smaller and smaller, the need for very fine-pitch solder-ball placement and wafer level packaging will become even more critical.

About Pac Tech

Pac Tech – Packaging Technologies GmbH, founded 1995 with facilities in Nauen and Berlin, Germany and Santa Clara, California is a leading equipment company for wafer bumping equipment and specializes in electroless nickel under-bump metallization and solder-ball bumping using lasers. Since its inception, Pac Tech has received 20 patents for products developed in areas relating to wafer bumping, flip-chip and chip-scale packaging, and laser-bonding technology. Its website is www.pactech.de.